

UNITED STATES PATENT AND TRADEMARK OFFICE

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BEFORE THE PATENT TRIAL AND APPEAL BOARD

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TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.,

and

APPLE INC.,

Petitioners

v.

MYW SEMITECH, LLC,

Patent Owner

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*Inter Partes* Review Case No. IPR2026-00066  
U.S. Patent No. 11,538,763

**PETITIONERS' UPDATED EXHIBIT LIST**

Petitioners submit this updated Appendix of Exhibits with newly-filed Exhibit 1138.

### APPENDIX OF EXHIBITS

<b>Exhibit 1001</b>	U.S. Patent No. 11,538,763
<b>Exhibit 1002</b>	File History of the '763 Patent
<b>Exhibit 1003</b>	Declaration of Stanley Shanfield, Ph.D.
<b>Exhibit 1004</b>	U.S. Patent No. 9,167,694 to Sundaram, et al.
<b>Exhibit 1005</b>	U.S. Patent Publication No. 2010/0290191 to Lin, et al.
<b>Exhibit 1006</b>	U.S. Patent Publication No. 2011/0215458 to Camacho, et al.
<b>Exhibit 1007</b>	U.S. Patent No. 9,679,863 to Lin, et al.
<b>Exhibit 1008</b>	U.S. Patent Publication 2011/0266691 to Lin, et al.
<b>Exhibit 1009</b>	Intentionally left blank
<b>Exhibit 1010</b>	U.S. Patent No. 9,123,763 to Yu, et al.
<b>Exhibit 1011</b>	U.S. Patent Publication 2014/0035935 to Shenoy, et al.
<b>Exhibit 1012</b>	Andrea Chen, et al. <i>Semiconductor Packaging Materials Interaction and Reliability</i> , CRC Press, 2012
<b>Exhibit 1013</b>	Philip Garrou, et al., <i>RDL: an integral part of today's advanced packaging technologies</i> , Solid State Technology, May 2011
<b>Exhibit 1014</b>	U.S. Patent No. 8,780,576 to Haba, et al.
<b>Exhibit 1015</b>	U.S. Patent No. 7,902,648 to Lee
<b>Exhibit 1016</b>	U.S. Patent No. 7,964,961 to Lee, et al.
<b>Exhibit 1017</b>	U.S. Patent No. 7,241,641 to Savastiouk, et al.
<b>Exhibit 1018</b>	U.S. Patent Publication No. 2005/0110168 to Chuang
<b>Exhibit 1019</b>	U.S. Patent Publication No. 2011/0026232 to Lin, et al.
<b>Exhibit 1020</b>	U.S. Patent No. 5,086,558 to Grube, et al.
<b>Exhibit 1021</b>	U.S. Patent Publication No. 2011/0193219 to Lai, et al.
<b>Exhibit 1022</b>	U.S. Patent No. 6,818,545 to Lee, et al.
<b>Exhibit 1023</b>	U.S. Patent No. 6,974,659 to Su, et al.
<b>Exhibit 1024</b>	U.S. Patent Publication No. 2006/0175686 to Murata, et al.
<b>Exhibit 1025</b>	U.S. Patent Publication No. 2012/0098124 to Wu, et al.
<b>Exhibit 1026</b>	U.S. Patent No. 8,193,604 to Lin et al.
<b>Exhibit 1027</b>	U.S. Patent Publication No. 2004/0203224 to Halahan, et al.

<b>Exhibit 1028</b>	Philip Garrou, <i>Introduction to 3D Integration</i> , Handbook of 3D integration: Volumes 1 and 2, Technology and Application of 3D Integrated Circuits, 2012
<b>Exhibit 1029</b>	U.S. Patent Publication No. 2003/0068877 to Kinsman
<b>Exhibit 1030</b>	U.S. Patent Publication No. 2010/0246152 to Lin, et al.
<b>Exhibit 1031</b>	Yi Yang, et al, <i>CPU-Assisted GPGPU on Fused CPU-GPU Architectures</i> , IEEE Xplore
<b>Exhibit 1032</b>	File History of U.S. Patent No. 11,107,768
<b>Exhibit 1033</b>	U.S. Patent No. 4,863,773 to Rousseau, et al.
<b>Exhibit 1034</b>	U.S. Patent No. 6,365,265 to Tose, et al.
<b>Exhibit 1035</b>	E.D. Blackshear, et al., <i>The evolution of build-up package technology and its design challenges</i> , International Business Machines Corporation, 2005
<b>Exhibit 1036</b>	Intentionally Left Blank
<b>Exhibit 1037</b>	U.S. Patent No. 7,374,969 to Cho, et al.
<b>Exhibit 1038</b>	U.S. Patent No. 7,199,036 to Chan, et al.
<b>Exhibit 1039</b>	U.S. Patent No. 8,158,508 to Lin, et al.
<b>Exhibit 1040</b>	U.S. Patent No. 6,619,538 to Test, et al.
<b>Exhibit 1041</b>	U.S. Patent Publication No. 2011/0101523 to Hwang, et al.
<b>Exhibit 1042</b>	U.S. Patent No. 6,831,003 to Huang, et al.
<b>Exhibit 1043</b>	U.S. Patent Publication No. 2009/0226611 to Suzuki, et al.
<b>Exhibit 1044</b>	U.S. Patent No. 6,077,726 to Mistry, et al.
<b>Exhibit 1045</b>	U.S. Patent Publication No. 2010/0244245 to Pendse, et al.
<b>Exhibit 1046</b>	U.S. Patent Publication No. 2012/0206160 to Wu, et al.
<b>Exhibit 1047</b>	U.S. Patent Publication No. 2009/0174052 to Sogawa, et al.
<b>Exhibit 1048</b>	U.S. Patent Publication No. 2013/0100624 to Carpenter, et al.
<b>Exhibit 1049</b>	U.S. Patent No. 7,047,515 to Vitek, et al.
<b>Exhibit 1050</b>	U.S. Patent No. 8,116,097 to Love, et al.
<b>Exhibit 1051</b>	U.S. Patent Publication No. 2009/0237900 to Origuchi, et al.
<b>Exhibit 1052</b>	U.S. Patent Publication No. 2005/0002167 to Hsuan, et al.
<b>Exhibit 1053</b>	U.S. Patent Publication No. 2008/0067695 to Chow, et al.
<b>Exhibit 1054</b>	U.S. Patent No. 6,489,240 to Iacoponi, et al.
<b>Exhibit 1055</b>	U.S. Patent No. 6,578,178 to Mau
<b>Exhibit 1056</b>	U.S. Patent Publication No. 2012/0001190 to Okabe, et al.
<b>Exhibit 1057</b>	U.S. Patent No. 7,307,348 to Wood, et al.
<b>Exhibit 1058</b>	U.S. Patent No. 8,138,014 to Chi, et al.
<b>Exhibit 1059</b>	U.S. Patent No. 6,506,672 to Dagenais, et al.
<b>Exhibit 1060</b>	U.S. Patent No. 8,518,798 to Graetz
<b>Exhibit 1061</b>	U.S. Patent Publication No. 2009/0261473 to Lee, et al.

<b>Exhibit 1062</b>	U.S. Patent No. 6,440,289 to Woo, et al.
<b>Exhibit 1063</b>	U.S. Patent No. 6,812,143 to Lane, et al.
<b>Exhibit 1064</b>	U.S. Patent Publication No. 2012/0145552 to Nagai, et al.
<b>Exhibit 1065</b>	U.S. Patent Publication No. 2011/0147950 to Tsi, et al.
<b>Exhibit 1066</b>	U.S. Patent Publication No. 2009/0070727 to Solomon
<b>Exhibit 1067</b>	U.S. Patent Publication No. 2012/0098114 to Ishibashi
<b>Exhibit 1068</b>	U.S. Patent Publication No. 2011/0074028 to Pendse
<b>Exhibit 1069</b>	U.S. Patent No. 7,485,955 to Kang, et al.
<b>Exhibit 1070</b>	U.S. Patent Publication No. 2012/0104623 to Pagaila, et al.
<b>Exhibit 1071</b>	Intentionally left blank
<b>Exhibit 1072</b>	U.S. Patent No. 7,772,880 to Solomon
<b>Exhibit 1073</b>	U.S. Patent No. 7,989,270 to Huang, et al.
<b>Exhibit 1074</b>	U.S. Patent Publication No. 2011/0304999 to Yu, et al
<b>Exhibit 1075</b>	U.S. Patent Publication No. 2009/0117327 to Takada
<b>Exhibit 1076</b>	U.S. Patent Publication No. 2005/0081744 to Klocke, et al.,
<b>Exhibit 1077</b>	U.S. Patent No. 6,291,082 to Lopatin
<b>Exhibit 1078</b>	Intentionally left blank
<b>Exhibit 1079</b>	Intentionally left blank
<b>Exhibit 1080</b>	U.S. Patent Publication No. 2012/0319251 to Yu, et al.
<b>Exhibits 1081-1089</b>	Intentionally left blank
<b>Exhibit 1090</b>	U.S. Patent Publication No. 2005/0156280 to Patel, et al.
<b>Exhibits 1091-1092</b>	Intentionally left blank
<b>Exhibit 1093</b>	U.S. Patent No. 6,107,180 to Munroe, et al.
<b>Exhibit 1094</b>	U.S. Patent Publication No. 2011/0210283 to Ramirez, et al.
<b>Exhibit 1095</b>	U.S. Patent No. 6,452,502 to Dishongh, et al.
<b>Exhibit 1096</b>	U.S. Patent No. 6,344,401 to Lam.
<b>Exhibit 1097</b>	Richard K. Ulrich, et al., <i>Advanced Electronic Packaging</i> , IEEE Press Series on Microelectrical Systems, 2006
<b>Exhibit 1098</b>	Mulugeta Abteu, et al., <i>Lead-free Solders in Microelectronics</i> , Materials Science and Engineering, 2000
<b>Exhibit 1099</b>	Karl J. Puttlitz, et al., <i>Handbook of Lead-Free Solder Technology for Microelectronic Assemblies</i> , 2005
<b>Exhibit 1100</b>	U.S. Patent Publication No. 2013/0309832 to Cheng, et al.
<b>Exhibit 1101</b>	U.S. Patent Publication No. 2013/0151869 to Steinman, et al.
<b>Exhibit 1102</b>	Linely Gwennap, <i>Sandy Bridge Spans Generations: Intel Focuses on Graphics, Multimedia in New Processor Design</i> , Microprocessor, 2010

<b>Exhibit 1103</b>	U.S. Patent No. 6,330,164 to Khandros, et al.
<b>Exhibit 1104</b>	U.S. Patent No. 6,710,447 to Nogami.
<b>Exhibits 1105-1126</b>	Intentionally left blank
<b>Exhibit 1127</b>	U.S. Patent No. 8,238,113 to Iihola, et al.
<b>Exhibit 1128</b>	Intentionally left blank
<b>Exhibit 1129</b>	U.S. Patent No. 6,468,413 to Fanti, et al.
<b>Exhibit 1130</b>	U.S. Patent No. 8,132,775 to Goldmann.
<b>Exhibit 1131</b>	U.S. Patent Publication No. 2011/0186977 to Chi, et al.
<b>Exhibit 1132</b>	U.S. Patent No. 7,169,627 to Duh, et al.
<b>Exhibit 1133</b>	U.S. Patent No. 6,614,243 to Klehn, et al.
<b>Exhibit 1134</b>	U.S. Patent Publication No. 2009/0162622 to Van Veen, et al.
<b>Exhibit 1135</b>	U.S. Patent No. 6,570,259 to Alcoe, et al.
<b>Exhibit 1136</b>	U.S. Patent No. 7,741,567 to Beddingfield, et al.
<b>Exhibit 1137</b>	U.S. Patent No. 6,407,341 to Anstrom, et al.
<b>Exhibit 1138</b>	Email to Patent Owner's Counsel with Stipulation

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COUNSEL FOR PETITIONERS

**CERTIFICATE OF SERVICE ON PATENT OWNER  
UNDER 37 C.F.R. § 42.105**

Pursuant to 37 C.F.R. § 42.6(e), the undersigned certifies that on January 8, 2026, the foregoing *Petitioner's Updated Exhibit List and Exhibit 1138* were served via electronic filing with the Board and via Electronic Mail on the following counsel of record for Patent Owner:

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